ABSTRACT OF THE DISCLOSURE

A method of sealing an electronic component with molded resin comprises an electronic component setting step of engaging an electronic component (5) mounted on a lead frame (6) in mold cavities (3, 4) which are provided on mold surfaces of a fixed mold section (1) and a movable mold section (2) respectively to be opposed to each other, and a resin sealing step of charging a heated/melted resin material in the mold cavities (3, 4) engaged with the electronic component (5) and sealing the electronic component (5) received in the mold cavities (3, 4) and the lead frame (6) around the same in a resin mold package (7) corresponding to the shapes of the mold cavities (3, 4). The resin sealing step is carried out by applying a prescribed resin pressure to the resin charged in the mold cavities (3, 4) and thereafter pressing the resin received in the mold cavities (3, 4) against the lead frame (6) from the exterior.

According to this method, adhesion between the resin mold package (7) molded in the mold cavities (3, 4) and the lead frame (6) is improved, whereby these members are prevented from defining a clearance therebetween and water is prevented from infiltrating from therebetween, and the quality and the reliability of the product can be improved.

This Sheet Has Been Replaced